

# INFORMATION DISCLOSURE CITATION

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Sudipta K. Ray et al.

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## U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
hm	6,077,477	6/2000	Sakai et al.	420	580	
	5,527,628	6/1996	Anderson et al.	428	647	
	5,221,038	6/1993	Melton et al.	228	180	
	5,147,084	9/1992	Behun et al.	228	58.3	
	4,875,617	10/1989	Citowsky	228	123	
	4,778,733	10/1988	Lubrano et al.	428	647	
	3,716,907	2/1973	Anderson	29	470.9	
✓	2,105,405	1/1936	Chase			

## FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
hm	131,299	8/1919	Great Britain	—	—		
hm	68124	7/1991	Australia	—	—		

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

hm		BRAZING AND SOLDERING ALLOYS, 3/1962, Semi Conductor Data, Semi-Alloys Inc., 5 pages
hm		YOR919950085, Kang et al., FLIP CHIP INTERCONNECTIONS USING LEAD-FREE SOLDERS, 4 pages, 1996

EXAMINER

hm

DATE CONSIDERED

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\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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1b		Hanson, M., CONSTITUTION OF BINARY ALLOYS, 1985, Genium Publishing Corporation, 4 pages, Cp 1174 -1177
1b		Bath, J. et al., RESEARCH UPDATE: LEAD-FREE SOLDER ALTERNATIVES, Vol. 11, No. 5, May 2000, Circuit Assembly, pages 30-40.

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